Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	100223	(wafer$1 or substrate$1) and ((((front near3 surface) same (back or rear or bottom or backside)) or ((first near3 surface) same (second near3 surface)))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/07/12 12:36
L2	52594	L1 and (((front near3 surface) with (wafer or substrate)) or ((first near3 surface) with (wafer or substrate)))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/07/12 12:43
L3	8807	L2 and ((plasma or dry) same etch$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/07/12 12:40
L4	7090	L3 and (((back near3 surface) with (wafer or substrate)) or ((second near3 surface) with (wafer or substrate)))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/07/12 14:55
L5	1889	L4 and ((hole$1 or via or opening$1) with ((back near3 surface) or (second near3 surface)))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/07/12 14:57
L6	1503	L5 and ((hole$1 or via or opening$1) with through)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/07/12 14:57
L7	1416	L6 and ((hole$1 or via or opening$1) near5 through)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/07/12 13:12
L8	872	L7 and (((back near3 surface) or (second near3 surface)) with through)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/07/12 14:58
L9	867	L8 and ((form$5 or generat$3 or produc$3 or mak$3 or creat$3 or fabricat$3 or etch$3) with (hole$1 or via or opening$1))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/07/12 14:58

L10	49	L9 and (bak$3 with (resist$1 or photoresist$1))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/07/12 14:59
L11	52	L9 and (heat$3 with (resist$1 or photoresist$1))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/07/12 14:59
L12	93	L10 or L11	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/07/12 13:41
L13	7146	L3 and ((((back or backside) near3 surface) with (wafer or substrate)) or ((second near3 surface) with (wafer or substrate)))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/07/12 14:56
L14	1921	L13 and ((hole$1 or via or opening$1) with (((back or backside) near3 surface) or (second near3 surface)))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/07/12 14:57
L15	1534	L14 and ((hole$1 or via or opening$1) with through)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/07/12 14:57
L16	938	L15 and ((((back or backside) near3 surface) or (second near3 surface)) with through)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/07/12 14:58
L17	929	L16 and (((form$5 or generat$3 or produc$3 or mak$3 or creat$3 or fabricat$3 or etch$3) with (hole$1 or via or opening$1))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/07/12 14:58
L18	55	L17 and (bak$3 with (resist$1 or photoresist$1))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/07/12 14:59
L19	59	L17 and (heat$3 with (resist$1 or photoresist$1))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/07/12 14:59

L20	103	L18 or L19	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/07/12 14:59
L21	10	L20 not L12	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/07/12 15:06
L22	182	L17 and ((photoresist or resist) with ((backside or back or lower or second) near3 surface))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/07/12 15:09
L23	138	L22 not L20	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/07/12 15:09